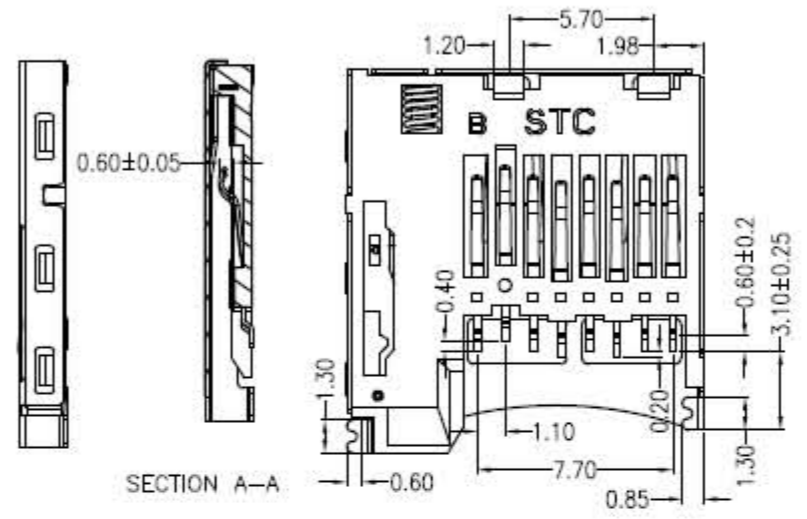
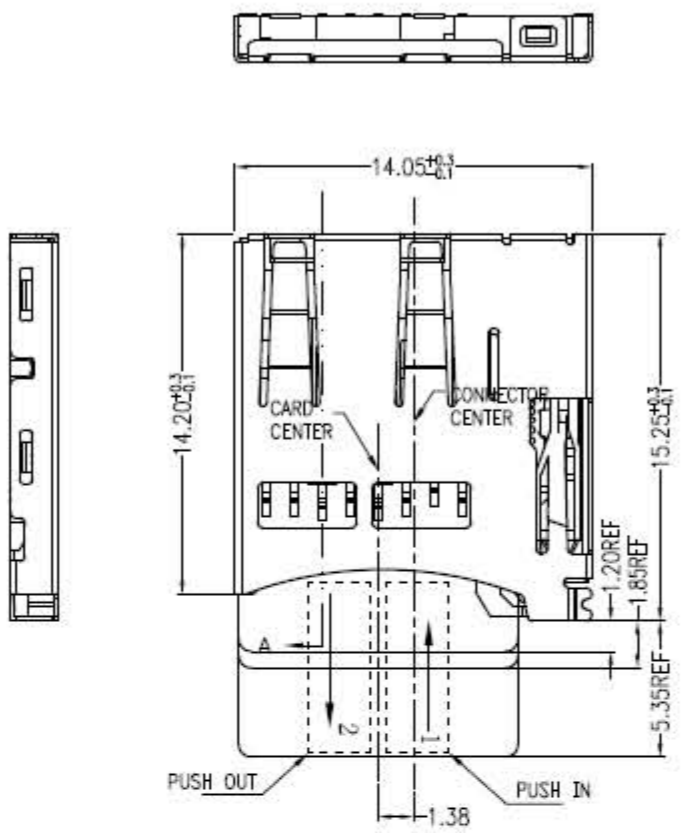
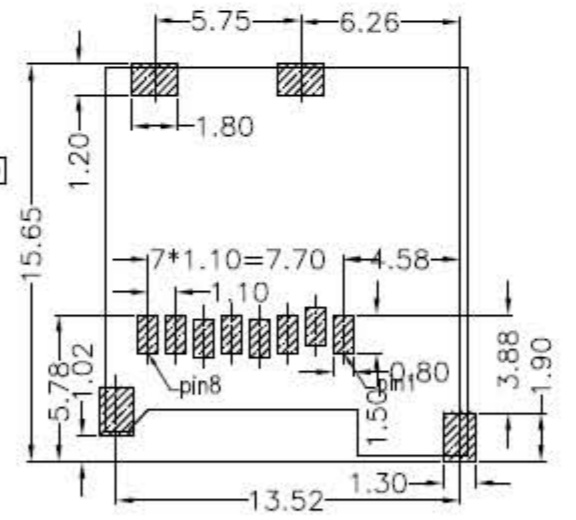
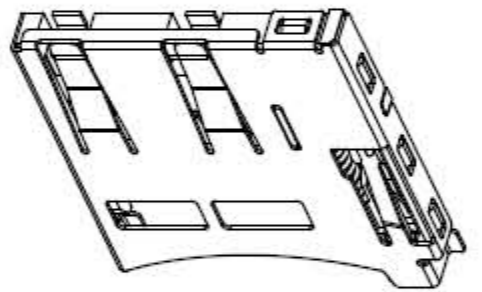


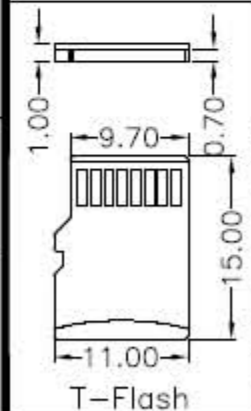
REV.	DESCRIPTION	APPD	DATE



- NOTES:
- MATERIAL:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0,COLOR:BLACK.
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL.
 - PLATING:
UNDERPLATE: NICKEL.
CONTACT AREA: GOLD OVER NICKEL.
SOLDER AREA: TIN OVER NICKEL.
 - MULTIMEDIA CARD COMPATIBLE



RECOMMENDED P.C.B HOLE LAYOUT COMPONENT SIDE VIEW(TOLERANCE: +/-0.05)



PIN NO.	NAME	YTYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DAT0	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(BIT1)

PART NO: TSNF2-EBS1-1111		MATERIAL:		RUI CHI	
MODEL NO:		FINISH:			
UNIT: MM	SIZE: A4	COLOR:		TITLE: micro-SD SMD 8pin ejector 02A	
TOLERANCES: X.X=±0.35 X.XX=±0.25 X.XXX=±0.15		GENERAL ANGLE: X.X=±3.0° X.XX=±2.0°		DR: 杨凯 0410'10	
APP:		CHK:		DWG NO:	REV: B/1
SCALE: 1:1		SHEET: 1 OF 2			